

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2857cdd-1#trpbf

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

(printed on: 2020-07-11 19:09:22)

TOTAL MASS (g) : 0.023369

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|---------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001553 | 1000000 | 66454.4921875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.009350 | 975000 | 400096.28125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000230 | 24000 | 9841.94042969 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000003 | 300 | 128.373138428 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000007 | 700 | 299.537322998 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.009590 | 1000000 | 410366.125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000437 | 1000000 | 18715.75 | | |
| | | External Plating Total: | | | | 0.000437 | 1000000 | 18715.75 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000218 | 1000000 | 9328.44824219 | | |
| Internal Plating Total: | | | | 0.000218 | 1000000 | 9328.44824219 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000764 | 750000 | 32692.3574219 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000255 | 250000 | 10911.7158203 | | |
| Die Attach Total: | | | | 0.001019 | 1000000 | 43604.0703125 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.001368 | 130000 | 58538.1484375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.009047 | 860000 | 387130.5625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000105 | 10000 | 4493.05957031 | | |
| | | Encapsulation Total: | | | | 0.010520 | 1000000 | 450161.78125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000032 | 1000000 | 1369.31347656 | | |
| | | | | | TOTAL MASS (g) : | 0.023369 | | |